US 20170098578A1

(19) United States

(12) Patent Application Publication

LEE et al.

(10) Pub. No.: US 2017/0098578 A1

(43) Pub. Date: Apr. 6, 2017

(54) **METHOD OF FABRICATING A SEMICONDUCTOR PACKAGE**

(71) Applicant: **SAMSUNG ELECTRONICS CO., LTD.**, SUWON-SI (KR)

(72) Inventors: **JANGWOO LEE**, CHEONAN-SI (KR); **YOUNGDOO JUNG**, SUWON-SI (KR)

(73) Assignee: **SAMSUNG ELECTRONICS CO., LTD.**, SUWON-SI (KR)

(21) Appl. No.: **15/158,890**

(22) Filed: **May 19, 2016**

(30) **Foreign Application Priority Data**

Oct. 5, 2015 (KR) 10-2015-0139724

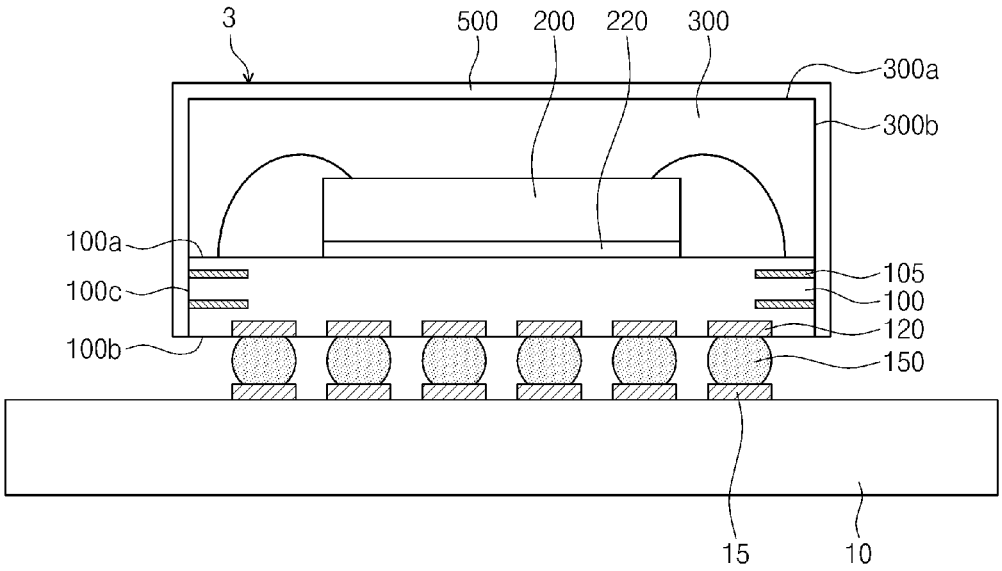
Publication Classification

(51) **Int. Cl.**

H01L 21/78 (2006.01)
H01L 23/00 (2006.01)
H01L 21/02 (2006.01)

(52) **U.S. Cl.**

CPC ***H01L 21/78*** (2013.01); ***H01L 21/02076*** (2013.01); ***H01L 24/81*** (2013.01); ***H01L 24/03*** (2013.01); ***H01L 24/11*** (2013.01)

(57) **ABSTRACT**

A method of fabricating a semiconductor package is disclosed. The method includes forming a plurality of semiconductor chips and a mold layer covering the semiconductor chips on a substrate, forming outer terminals on a bottom surface of the substrate, coating a water-soluble material on the bottom surface of the substrate and the outer terminals to form a coating layer, cutting the substrate and the mold layer to separate the semiconductor chips from each other, and forming a shielding layer on the cutted mold layer.